

AMENDMENTS TO THE SPECIFICATION

Amend the paragraph bridging pages 2-3 of the specification as indicated:

This die bonding layer composed of the curable epoxy resin composition is improved in adhesion in moist conditions, adhesion at elevated temperature and strength, but sometimes hinders the chips as diced from being picked up. More particularly, the radiation-polymerizable adhesive layer which controls the adhesion between the substrate and the die bonding layer as reported in Japanese Patent No. 2,984,549 is formed of a composition comprising a (meth)acrylate copolymer, (meth)acrylic radical-containing polymer or polyfunctional acrylic compound and a photo-polymerization initiator. This composition is compatible with the die bonding layer. On account of reaction due to UV exposure or fusion between the adhesive and the die bonding layer which is softened by heat compression for wafer holding in the dicing step, the tack strength is increased to prevent the chips from being easily picked up. The tack strength (or adhesive property) between the die bonding layer and the ~~silicone~~ radiation-polymerizable adhesive layer changes or increases with the passage of time, also preventing the chips from being easily picked up.